

Notes/Revision Information

V0.03 - 11/22/2013

V0.04 - 2/21/2014

- Updated U35 package to DSG

V0.05 - 02/26/2014

p6

- Reassigned pin10(Connector J1) ZC connection to GPIO_63(U32)

p4

- Pin 39 of U17 tied to GND

- Changed Pin 37 of U17 to floating

V0.06 - 08/28/2014

p5

- updated R100, L46, C140, C141, L45 Values

- Added R121, L52, L53, C166, C167


p2

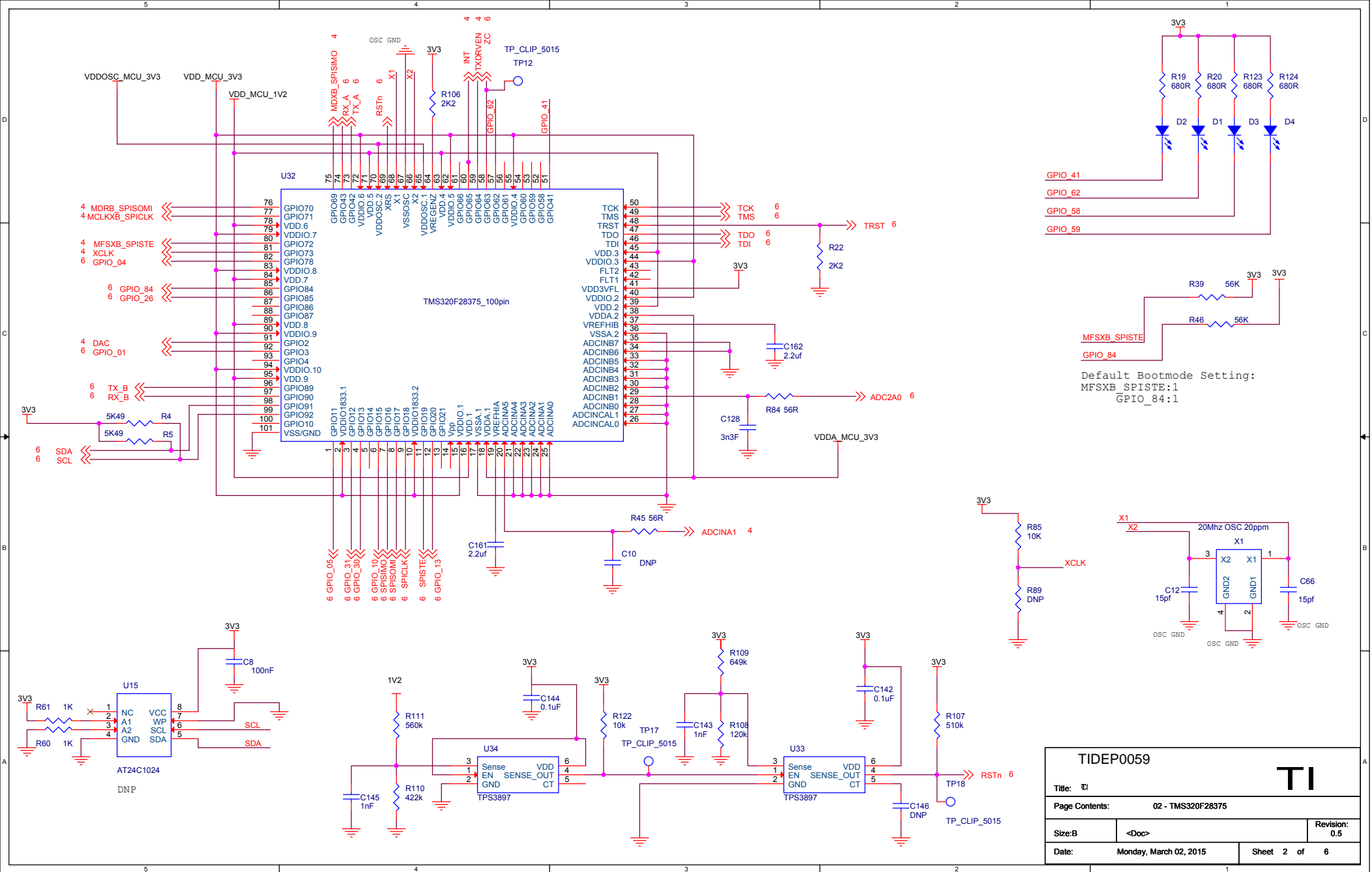
- Tied unused ADC pins to GND

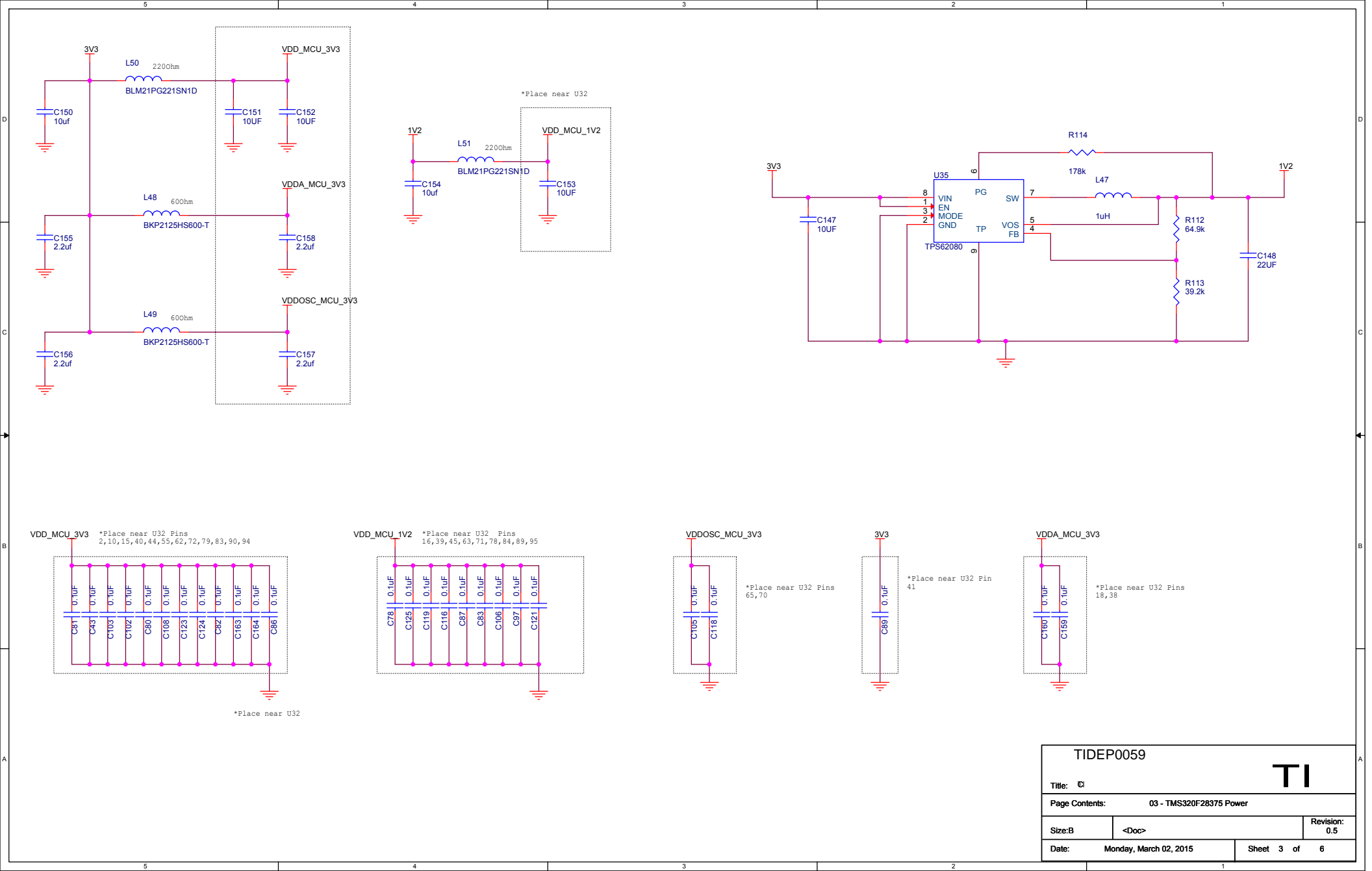
- Added R122

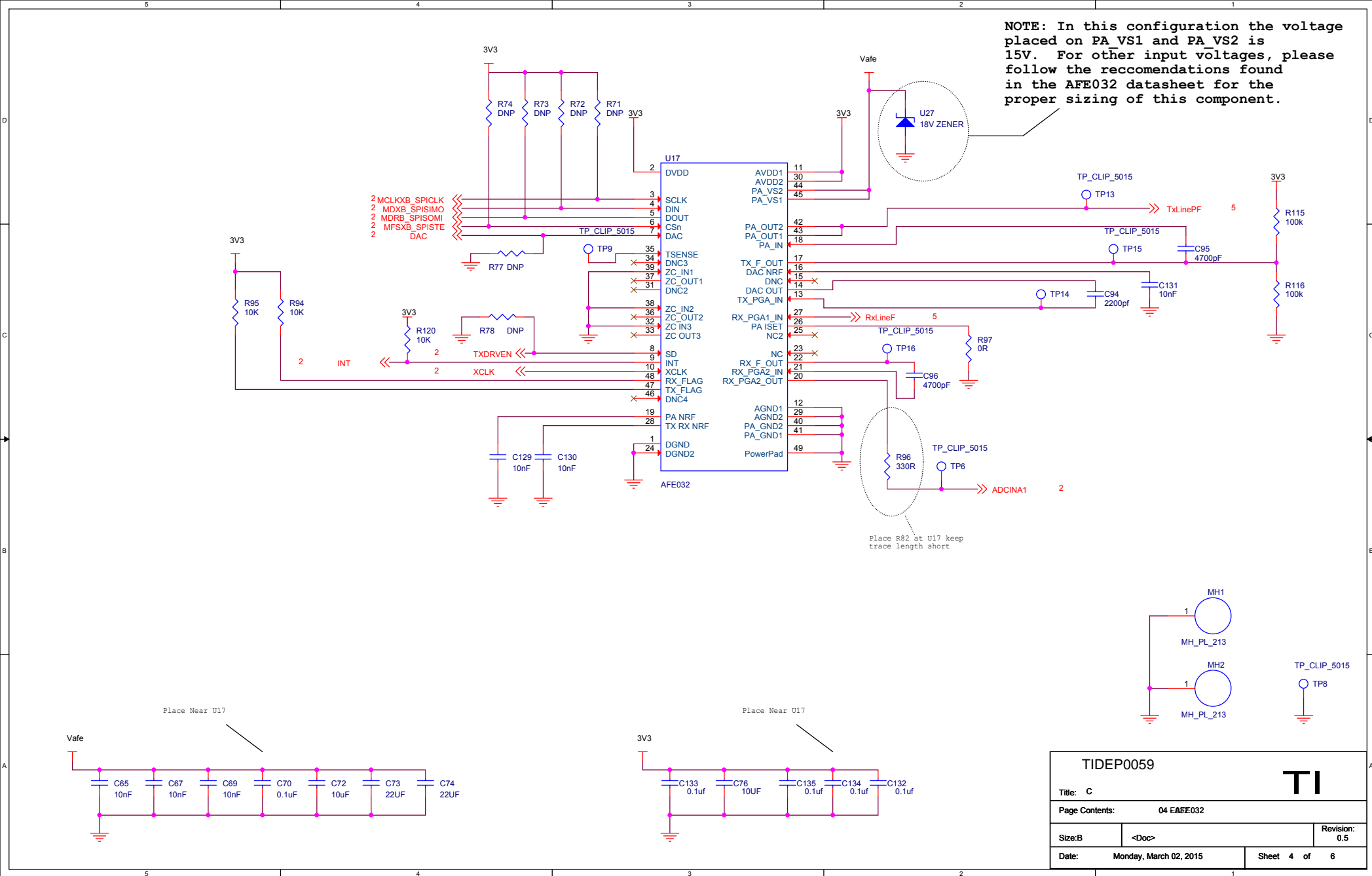
- Added LED's D3, D4

- 01 - Title Page
- 02 - SOMPLC CEN
- 03 - SOMPLC-CEN Power
- 04 - AFE32
- 05 - BPF
- 06 - Connector

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| TIDEP0059 | | |
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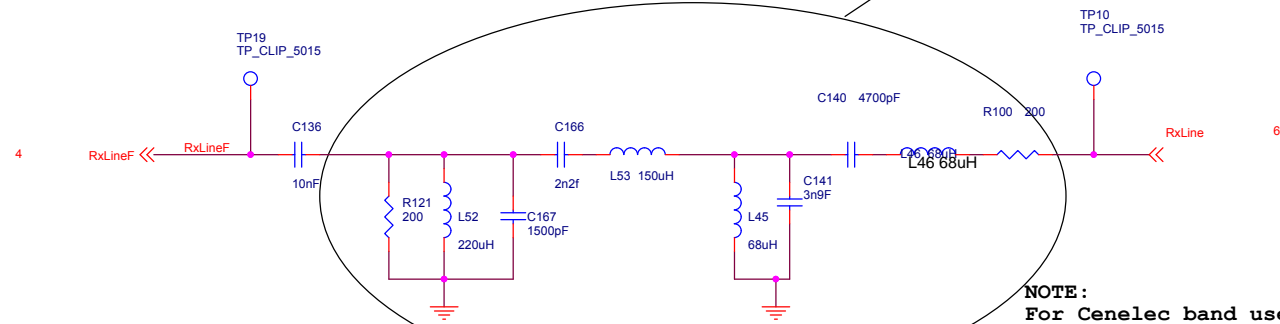




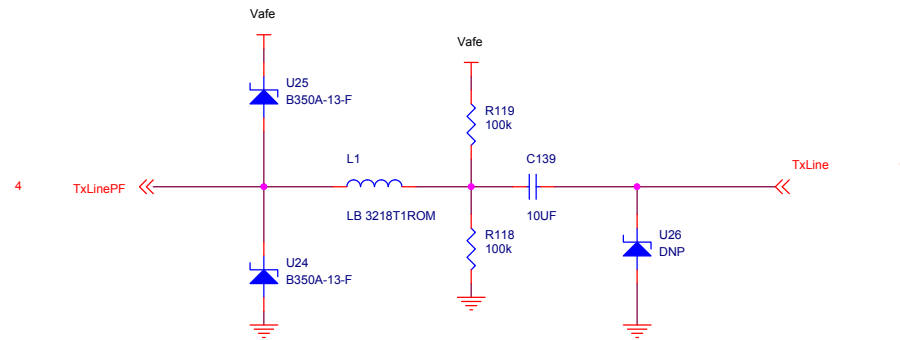


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| TIDEP0059 | | | | TI | |
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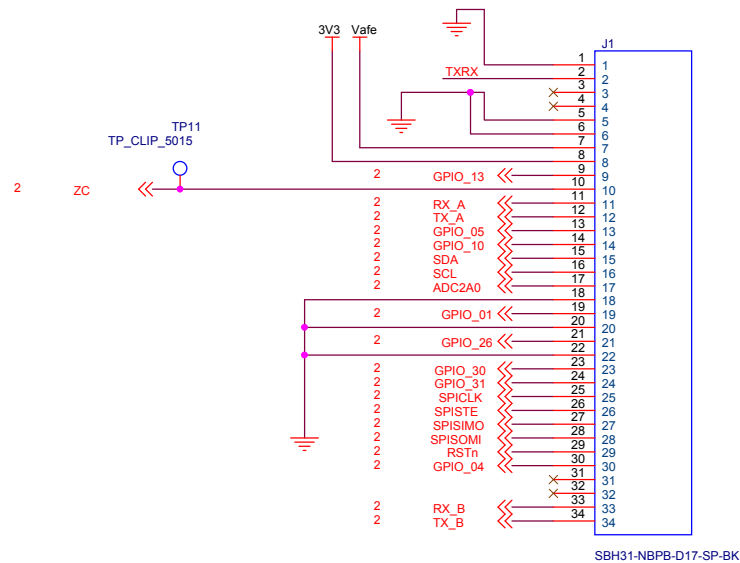
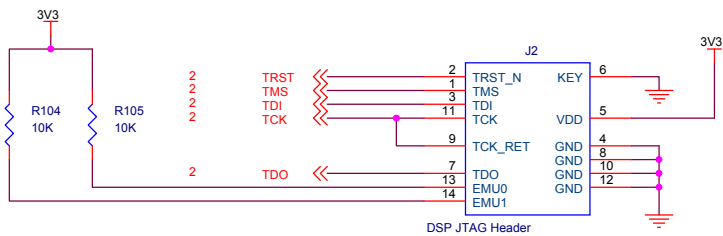
NOTE: Use Values below for CENELEC Band



NOTE:
For Cenelec band use values below:
R100 - 150 ohm
L46 - 330uH
C140 - 0.022uF
C141 - 0.033uF
L45 - 180uH
L53 - 1mH
C166 - 8200pF
C167 - 0.015uF
L52 - 470uH
R121 - 150 ohm



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| TIDEP0059 | | TI | |
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